

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of the claims in the application:

Listing of Claims:

CLAIMS

1. (Currently Amended) A polish pad comprising:
a base layer; ~~and~~
a first resin layer including a first surface and a second surface, the first surface coupled to the base layer; and
a second resin layer including an ion exchange material therein, the second resin layer coupled to the second surface of the first resin layer and configured to have a patterned surface. layer contiguously disposed in the base layer wherein at least one of the base layer and the ion exchange layer is patterned.
2. (Original) The polish pad of claim 1, wherein the ion exchange layer comprises ion exchange resin beads.
3. (Previously Presented) The polish pad of claim 1, wherein the ion exchange layer comprises ground ion exchange resin beads.
4. (Previously Presented) The polish pad of claim 2, wherein the ion exchange beads are embedded in the ion exchange layer.
5. (Previously Presented) The polish pad of claim 3, wherein the ground ion exchange beads are embedded in the ion exchange layer.
- 6.-9. (Canceled)
10. (Original) The polish pad of claim 1, wherein the ion exchange layer binds cations.

11. (Original) The polish pad of claim 10, wherein the ion exchange layer binds copper cations.
12. (Currently Amended) An ion exchange polish pad, comprising:
a base layer; and
a ~~contiguous~~ first resin layer configured to have a pattern and coupled to the base layer; ~~and having~~
a second resin layer including an ion exchange material embedded therein,
wherein the second resin layer is conformed and coupled to the first resin layer. ~~at least one of the base layer and the resin layer is patterned.~~
13. (Original) The ion exchange polish pad of claim 12, wherein the ion exchange material is ion exchange resin beads.
14. (Original) The ion exchange polish pad of claim 12, wherein the ion exchange material is ion exchange resin powder.
- 15-32 (Canceled)
33. (New) A one layer ion exchange polishing pad, comprising:
a resin layer including an ion exchange material dispersed therein and coupled to a polishing platform.
34. (New) The ion exchange pad of claim 1, wherein the patterned surface of the second resin layer is a stenciled pattern.
35. (New) The ion exchange pad of claim 1, wherein the patterned surface of the second resin layer is an etched pattern.
36. (New) The ion exchange pad of claim 1 further comprising an adhesive coating to couple the first resin layer to the base layer.